

ABSTRACT

A microelectronic package comprises a tubular housing and a microelectronic assembly affixed to a support that is received in the housing. The support may be a cage-like structure that comprises axial ribs to which the microelectronic assembly is attached. Alternately, the support may comprise a solid surface for affixing a flexible substrate. The microelectronic assembly is arranged with a major surface facing and spaced apart from the inner wall of the housing. Thus, the microelectronic assembly is proximate to the wall to provide an optimum volume for packaging other components. Moreover, the spacing between the microelectronic assembly and the tubular housing facilitates coolant gas flow during use to enhance thermal dissipation.